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features common to all types

- Single 5-V Supply
- 3-State Driver Output Circuitry
- TTL-Compatible Driver Inputs
- TTL-Compatible Receiver Output
- Differential Line Operation
- Receiver Output Strobe (SN55116, SN75116, SN75117) or Enable (SN75118, SN75119)
- Designed for Party-Line (Data-Bus) Applications

additional features of the SN55116/SN75116

- Choice of Ceramic or Plastic Packages
- Independent Driver and Receiver
- Choice of Open-Collector or Totem-Pole Outputs on Both Driver and Receiver
- Dual Data Inputs on Driver
- Optional Line-Termination Resistor in Receiver
- ±15-V Receiver Common-Mode Capability
- Receiver Frequency-Response Control

additional features of the SN75117

 Driver Output Internally Connected to Receiver Input

The SN75118 is an SN75116 With 3-State Receiver Output Circuitry The SN75119 is an SN75117 With 3-State Receiver Output Circuitry

description

These integrated circuits are designed for use in interfacing between TTL-type digital systems and differential data-transmission lines. They are especially useful for party-line (data-bus) applications. Each of these circuit types combine in one package a 3-state differential line driver and a differential-input line receiver, both of which operate from a single 5-V power supply. The driver inputs and the receiver outputs are TTL compatible. The driver employed is similar to the SN55113 and SN75113 3-state line drivers, and the receiver is similar to the SN55115 and SN75115 line receivers.

The SN55116, SN75116, and SN75118 offer all the features of the SN55113 and SN75113 drivers and the SN55115 and SN75115 receivers combined. The driver performs the dual input AND and NAND functions when enabled or presents a high impedance to the load when in the disabled state. The driver output stages are similar to TTL totem-pole outputs, but have the current-sinking portion separated from the current-sourcing portion and both are brought out to adjacent package terminals. This feature allows the user the option of using the driver in the open-collector output configuration, or, by connecting the adjacent source and sink terminals together, of using the driver in the normal totem-pole output configuration.

The receiver portion of the SN55116, SN75116, and SN75118 features a differential-input circuit having a common-mode voltage range of \pm 15 V. An internal 130- Ω equivalent resistor also is provided, which optionally can be used to terminate the transmission line. A frequency-response control terminal allows the user to reduce the speed of the receiver or to improve differential noise immunity. The receivers of the SN55116 and SN75116 have an output strobe and a split totem-pole output. The receiver of the SN75118 has an output-enable for the 3-state split totem-pole output. The receiver section of either circuit is independent of the driver section except for the V_{CC} and ground terminals.

The SN75117 and SN75119 provide the basic driver and receiver functions of the SN55116, SN75116, and SN75118, but use a package that is only half as large. The SN75117 and SN75119 are intended primarily for party-line or bus-organized systems because the driver outputs are internally connected to the receiver inputs. The driver has a single data input and a single enable input. The SN75117 receiver has an output strobe, while the SN75119 receiver has a 3-state output enable. However, these devices do not provide output connection options, line-termination resistors, or receiver frequency-response controls.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

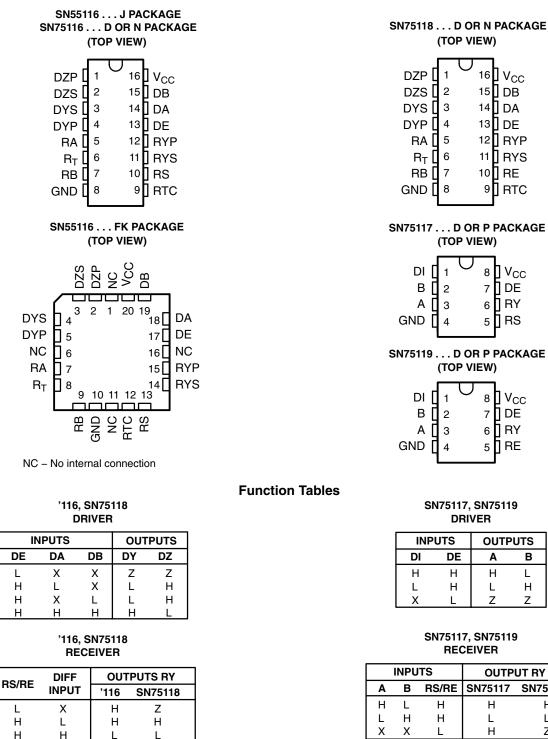


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description (continued)

The SN55116 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN75116, SN75117, SN75118, and SN75119 are characterized for operation from 0°C to 70°C.



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H = high level ($V_I \ge V_{IL}$ min or V_{ID} more positive than V_{TL} max), L = low level ($V_I \le V_{IL}$ max or V_{ID} more negative than V_{TL} max), X = irrelevant, Z = high impedance (off)

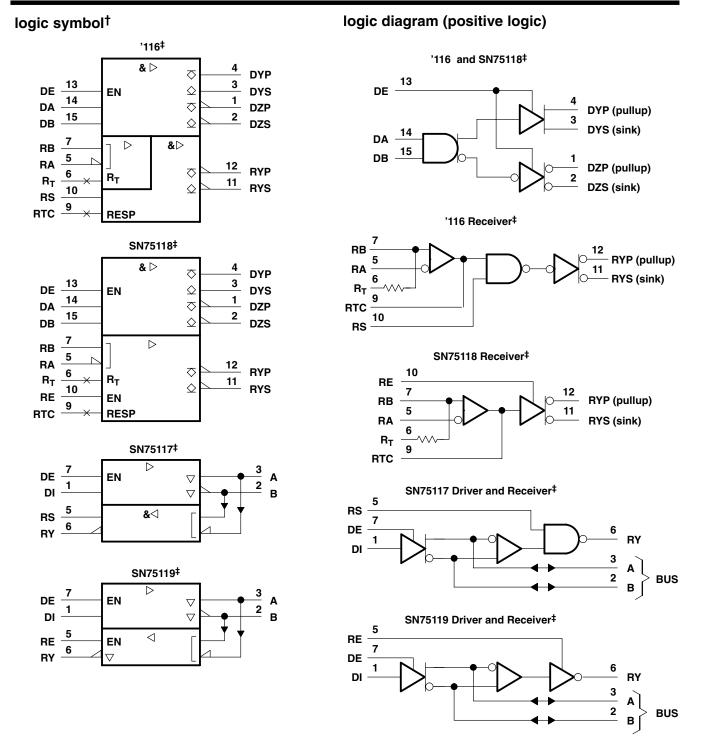


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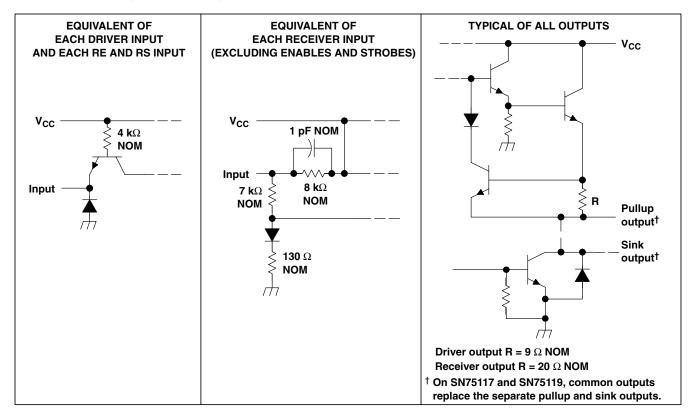
[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

[‡] Pin numbers shown for the SN55116 and SN75116 are for the D, J, and N packages, those shown for the SN75118 are for the D and N packages, and those shown for SN75117 and SN75119 are for the D and P packages.



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schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature (unless otherwise noted)[‡]

Supply voltage, V _{CC} (see Notes 1 and 2)	
Input voltage, V _I : DA, DB, DE, DI, RE, and RS	5.5 V
RA, RB, R _T for '116, SN75118 only	±25 V
A and B for SN75117, SN75119 only	0 to 6 V
Off-state voltage applied to open-collector outputs: '116, SN75118 only	12 V
Continuous total power dissipation (see Note 2)	See Dissipation Rating Table
Storage temperature range, T _{sta}	–65°C to 150°C
Case temperature for 60 seconds, T _C : FK package	
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: J package	300°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D, N, or P pack	age 260°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to the network ground terminal.

2. In the FK and J packages, the SN55116 chip is alloy mounted. The SN75116, SN75117, SN75118, and SN75119 chips are glass mounted.



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		DISSIPATION RATING TA	BLE	
PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 125°C POWER RATING
D (8 pin)	725 mW	5.8 mW/°C	464 mW	—
D (16 pin)	950 mW	7.6 mW/°C	608 mW	—
FK	1375 mW	11.0 mW/°C	880 mW	275 mW
J	1375 mW	11.0 mW/°C	880 mW	275 mW
N	1150 mW	9.2 mW/°C	736 mW	—
Р	1000 mW	8.0 mW/°C	640 mW	—

recommended operating conditions

PARAMETER		5	SN55116		SN751 SN751	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V _{CC}		4.5	5	5.5	4.5	5	5.5	V
High-level input voltage, V _{IH}	All inputs except differential	2			2			V
Low-level input voltage, VIL	inputs			0.8			0.8	V
	Drivers			-40			-40	
High-level output current, I _{OH}	Receivers			-5			-5	mA
	Drivers			40			40	
Low-level output current, I _{OL}	Receivers			15			15	mA
	'116, SN75118			±15			±15	
Receiver input voltage, V _I	SN75117, SN75119	0		6	0		6	V
	'116, SN75118			±15			±15	
ommon-mode receiver input voltage, V_{ICR}	SN75117, SN75119	0		6	0		6	V
Operating free-air temperature, T _A	÷	-55		125	0		70	°C



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

driver section

						'116	6, SN751	18	SN751			
	PARAMETER			TEST CONDITIONS [†]		MIN	TYP‡	MAX	MIN	TYP [‡]	MAX	UNIT
V _{IK}	Input clamp voltage		$V_{CC} = MIN$,	l _l = – 12 mA			-0.9	-1.5		-0.9	-1.5	V
			V _{CC} = MIN,	$T_A = 25^{\circ}C \text{ (SN55116)},$ $T_A = 0^{\circ}C \text{ to } 70^{\circ}C$	I _{OH} = - 10 mA	2.4	3.4		2.4	3.4		
V _{OH}	High-level output voltage	vel output voltage		(SN75116, SN75117, SN75118, SN75119)	I _{OH} = -40 mA	2	3		2	3		v
			I _{IH} = 2 V	$T_A = -55^{\circ}C$ to $125^{\circ}C$	$I_{OH} = -10 \text{ mA}$	2			2			
				(SN55116)	$I_{OH} = -40 \text{ mA}$	1.8			1.8			
V _{OL}	Low-level output voltage		$V_{CC} = MIN$,	$V_{IH} = 2 V$, $V_{IL} = 0.8 V$,	I _{OL} = 40 mA			0.4			0.4	V
V _{OK}	Output clamp voltage		$V_{CC} = MAX,$	$I_0 = -40 \text{ mA}, \text{DE at } 0.8 \text{ V}$				-1.5			-1.5	V
				$T_A = 25^{\circ}C$			1	10				
10/10	Off-state open-collector out	tout current	V _{CC} = MAX,		SN55116			200				μA
I _{O(off)}		iput current	V _O = 12 V	$T_A = MAX$	SN75116, SN75118			20			μ	μΑ
			$V_{CC} = MAX,$	$V_{O} = 0$ to V_{CC} , DE at 0.8 V,	$T_A = 25^{\circ}C$			±10				
	Off state (bigh immediates	- 4 - 4 - 2		V _O = 0	SN55116			-300	00			
I _{OZ}	Off-state (high-impedance- output current	state)	V _{CC} = MAX, DE at 0.8 V,	$V_{O} = 0.4 \text{ V to } V_{CC}$	SN55116			±150				μA
			$T_A = MAX$	$V_{O} = 0$ to V_{CC}	SN75116, SN75118			±20				
I _I	Input current at maximum input voltage	Driver or	$V_{CC} = MAX,$	V _I = 5.5 V				1			1	mA
IIH	High-level input current	enable input	$V_{CC} = MAX,$	V _I = 2.4 V				40			40	μA
IIL	Low-level input current	1	$V_{CC} = MAX,$	V _I = 0.4 V				-1.6			-1.6	mA
los	Short-circuit output current	§	$V_{CC} = MAX,$	= MAX, $V_{O} = 0$, $T_{A} = 25^{\circ}C$				-120	-40		-120	mA
I _{CC}	Supply current (driver and combined)		V _{CC} = MAX,			42	60	42		60	mA	

[†] All parameters with the exception of off-state open-collector output current are measured with the active pullup connected to the sink output. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5$ V and $T_A = 25^{\circ}C$. § Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

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TEXAS INSTRUMENTS

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switching characteristics, V_{CC} = 5 V, C_L = 30 pF, T_A = 25°C

driver section

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	Propagation-delay time, low-to-high level output	0		14	30	
t _{PHL}	Propagation-delay time, high-to-low level output	See Figure 13		12	30	ns
t _{PZH}	Output-enable time to high level	$R_L = 180 \Omega$, See Figure 14		8	20	ns
t _{PZL}	Output-enable time to low level	$R_L = 250 \Omega$, See Figure 15		17	40	ns
t _{PHZ}	Output-disable time from high level	$R_L = 180 \Omega$, See Figure 14		16	30	ns
t _{PLZ}	Output-disable time from low level	$R_L = 250 \Omega$, See Figure 15		20	35	ns



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

receiver section

					Touot	'110	6, SN751	18	SN751	17, SN7	5119			
	PARAMETER			TEST COND	TIONST	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT		
N		h	V _O = 0.4 V,	l _{OL} = 15 mA,	$V_{CC} = MIN, V_{ICR} = 0,$ See Note 4			0.5			0.5	v		
V _{IT+}	Positive-going threshold vol	tages	See Note 3	-	$V_{CC} = 5 V$, $V_{ICR} = MAX$, See Note 5			1			1	v		
V _{IT-}	Negative-going threshold voltage§		Negeting aging threaded and the set		V _O = 2.4 V,	l _{OL} = -5 mA,	$V_{CC} = MIN, V_{ICR} = 0,$ See Note 4	-0.5 [¶]			-0.5¶			v
VII -	Negative-going threshold vo	Jilages	See Note 3		$V_{CC} = 5 V$, $V_{ICR} = MAX$, See Note 5	-1¶			-1¶			v		
Vi	Input voltage range#		V _{CC} = 5 V,	$V_{ID} = -1 V \text{ or } 1 V,$	See Note 3	15 to -15			6 to 0			V		
V _{OH}	High-level output voltage		I _{OH} = -5 mA,	$V_{CC} = MIN,$ $V_{ICR} = 0,$	$V_{ID} = -0.5 V$, See Notes 4 and 6	2.4			2.4			V		
∙он	nign-ievel output voltage		See Note 3	$V_{CC} = 5 V,$ $V_{ICR} = MAX,$	V _{ID} = – 1 V, See Note 5	2.4			2.4			v		
Max			l _{OL} = 15 mA,	$V_{CC} = MIN,$ $V_{ICR} = 0,$	$V_{ID} = 0.5 V$, See Notes 4 and 7			0.4			0.4	V		
V _{OL}	Low-level output voltage		See Note 3	$V_{CC} = 5 V,$ $V_{ICR} = MAX,$	V _{ID} = 1 V, See Note 5			0.4			0.4	v		
				$V_{I} = 0,$	Other input at 0 V		-0.5	-0.9		-0.5	-1			
I _{I(rec)}	I(rec) Receiver input current		V _{CC} = MAX, See Note 3	$V_{I} = 0.4 V,$	Other input at 2.4 V		-0.4	-0.7		-0.4	-0.8	mA		
				V _I = 2.4 V,	Other input at 0.4 V		0.1	0.3		0.1	0.4			
4	Input current at maximum Strobe		$V_{CC} = MIN,$ $V_{strobe} = 4.5 V$	$V_{ID} = -0.5 V,$	'116, SN75117			5			5	μ A		
	input voltage	Enable	$V_{CC} = MAX,$	V _I = 5.5 V	SN75118, SN75119			1			1	mA		

[†] Unless otherwise noted, V_{strobe} = 2.4 V. All parameters, with the exception of off-state open-collector output current, are measured with the active pullup connected to the sink output. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 ‡ All typical values are at V_{CC} = 5 V, T_A = 25°C, and V_{IC} = 0.

§ Differential voltages are at the B input terminal with respect to the A input terminal. Neither receiver input of the SN75117 or SN75119 should be taken negative with respect to GND.

[¶] The algebraic convention, where the less positive (more negative) limit is designated as minimum, is used in this data sheet for threshold voltages only.

[#] Input voltage range is the voltage range that, if exceeded at either input, will cause the receiver to cease functioning properly.

NOTES: 3. Measurement of these characteristics on the SN75117 and SN75119 requires the driver to be disabled with the driver enable at 0.8 V.

- 4. This applies with the less positive receiver input grounded.
- 5. For '116 and SN75118, this applies with the more positive receiver input at 15 V or the more negative receiver input at 15 V. For SN75117 and SN75119, this applies with the more positive receiver input at 6 V.

6. For SN55116, $V_{ID} = -1 V$

7. For SN55116, $V_{ID} = 1 V$

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receiver section (continued)

					o+	'11(6, SN751	18	SN751	17, SN7	5119	
	PARAMETER			TEST CONDITION	51	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
I _{IH}	High-level input current	Enable	$V_{CC} = MAX,$	V _I = 2.4 V	SN75118, SN75119			40			40	μA
l _i	Low-level input current	Strobe	V _{CC} = MAX, V _{strobe} = 0.4 V,	V _{ID} = 0.5 V, See Notes 4 and 7	'116, SN75117			-2.4			-2.4	mA
		Enable	$V_{CC} = MAX,$	V _I = 0.4 V	SN75118, SN75119			-1.6			-1.6	
I _(RTC)	Response-time-control curr	ent (RTC)	V _{CC} = MAX, RC at 0 V,	V _{ID} = 0.5 V, See Notes 4 and 7	$T_A = 25^{\circ}C$	-1.2						mA
			V _{CC} = MAX,	$T_A = 25^{\circ}C$			1	10				
I _{O(off)}	Off-state open-collector out	put current	$V_0 = 12 V_1$	T MAY	SN55116			200				μA
. ,			$V_{ID} = -1 V$	$T_A = MAX$	SN75116, SN75118			20				
	o <i>m</i>		V _{CC} = MAX,	$T_A = 25^{\circ}C$	SN75118, SN75119			±10			±10	
l _{OZ}	Off-state (high-impedance-s output current	state)	$V_0 = 0$ to V_{CC} ,	-	SN75118			±20				μA
	oupurouron		RE at 0.4 V	$T_A = MAX$	SN75119						±20	
R _T	Line-terminating resistance		$V_{CC} = 5 V$		$T_A = 25^{\circ}C$	77		167				Ω
I _{OS}	Short-circuit output current [§]		$V_{CC} = MAX,$ $V_{ID} = -0.5 V,$	V _O = 0, See Notes 4 and 6	$T_A = 25^{\circ}C$	-15		-80	-15		-80	mA
I _{CC}	Short current (driver and receiver combined)		V _{CC} = MAX, See Notes 4 and	V _{ID} = 0.5 V, 7	T _A = 25°C		42	60		42	60	mA

[†] Unless otherwise noted, V_{strobe} = 2.4 V. All parameters, with the exception of off-state open-collector output current, are measured with the active pullup connected to the sink output. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$, and $V_{IC} = 0$. § Not more than one output should be shorted at a time.

NOTES: 4. This applies with the less positive receiver input grounded.

6. For SN55116, $V_{ID} = -1 V$

7. For SN55116, V_{ID} = 1 V

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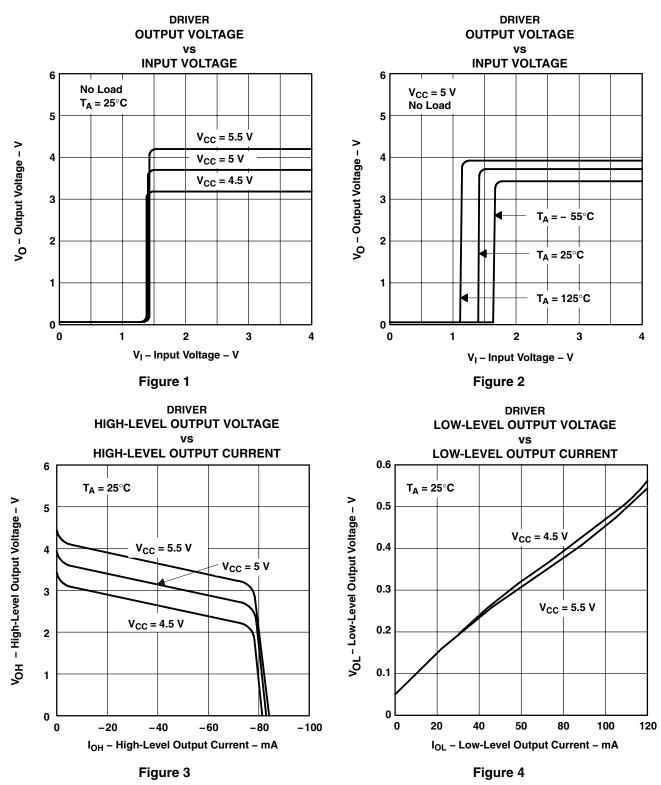
switching characteristics, V_{CC} = 5 V, C_L = 30 pF, T_A = 25°C

receiver section

	PARAMETER		TEST C	CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	Propagation-delay time, low-to-high-level output	D 400.0	0		20	75	ns	
t _{PHL}	Propagation-delay time, high-to-low-level output	R _L = 400 Ω,	See Figure 16		17	75	ns	
t _{PZH}	Output-enable time to high level	SN75118	$R_L = 480 \ \Omega$,	See Figure 14		9	20	ns
t _{PZL}	Output-enable time to low level	and	$R_L = 250 \ \Omega$,	See Figure 15		16	35	ns
t _{PHZ}			R _L = 480 Ω,	See Figure 14		12	30	ns
t _{PLZ}	Output-disable time from low level	evel only		See Figure 15		17	35	ns



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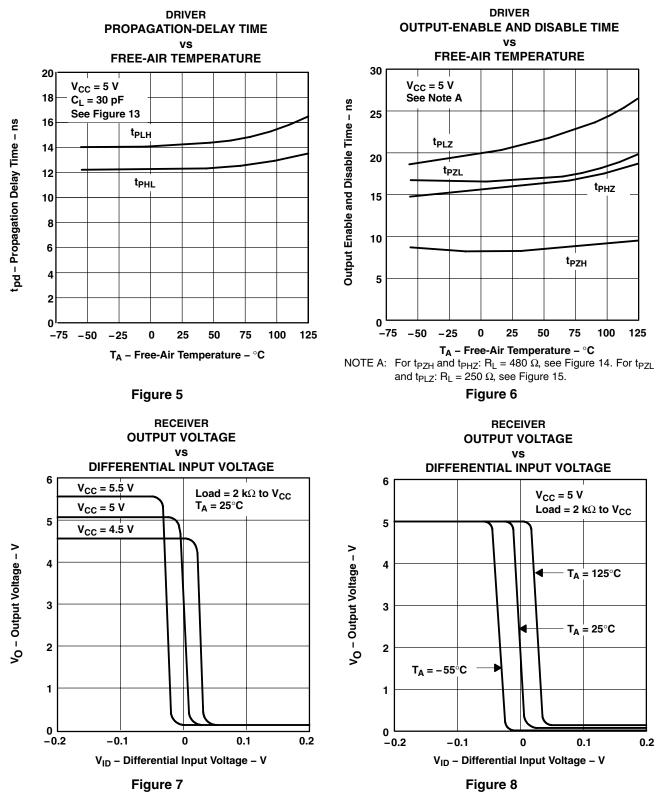
TYPICAL CHARACTERISTICS[†]

[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



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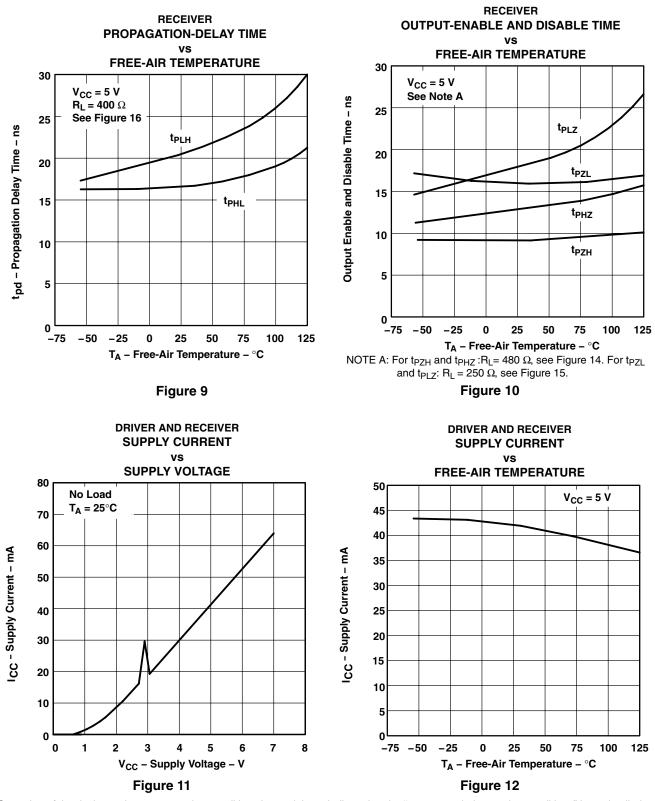




[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



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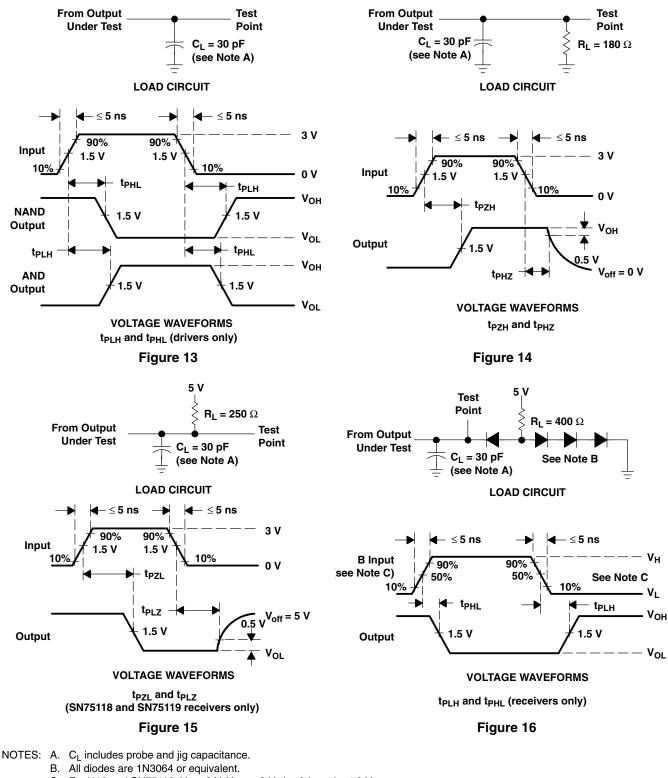


TYPICAL CHARACTERISTICS[†]

[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



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PARAMETER MEASUREMENT INFORMATION

- C. For '116 and SN75118, $V_H = 3 V$, $V_L = -3 V$, the A input is at 0 V.
 - For SN75117 and SN75119, $V_H = 3 V$, $V_L = 0$, the A input is at 1.5 V.
 - D. When testing the '116 and SN75118 receiver sections, the response-time control and the termination resistor pins are left open.





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-88511012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-8851101EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
SN55116J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
SN75116D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75116DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75116DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75116N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN75116NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN75116NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75116NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75116NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75117D	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	
SN75117P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN75117PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN75118D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	
SN75118N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN75118NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN75119D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
SN75119DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
SN75119DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
SN75119DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	



Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN75119DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
SN75119DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
SN75119P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN75119PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SNJ55116FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ55116J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN55116, SN75116 :



www.ti.com

5-Sep-2011

Catalog: SN75116

Military: SN55116

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com

TAPE AND REEL INFORMATION

REEL DIMENSIONS

Texas Instruments





TAPE AND REEL INFORMATION

TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

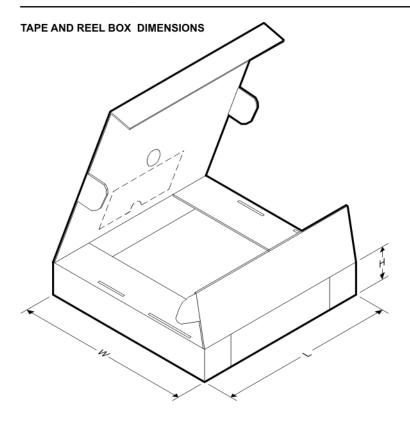
*All dimensions are nomina	I											
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75116NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN75119DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

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PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75116NSR	SO	NS	16	2000	367.0	367.0	38.0
SN75119DR	SOIC	D	8	2500	340.5	338.1	20.6

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



P(R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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